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**HORIKOSHI**(10) **Pub. No.: US 2024/0213287 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **SOLID-STATE IMAGING DEVICE AND  
ELECTRONIC APPARATUS**(52) **U.S. Cl.**  
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KANAGAWA (JP)(57) **ABSTRACT**(72) Inventor: **HIROSHI HORIKOSHI,**  
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A solid-state imaging device and an electronic apparatus include: a first pixel provided on a side of a first surface serving as a side from which light enters of a first base, and a second pixel that is disposed in a first direction on the first surface to be adjacent to the first pixel; a first signal terminal that is provided in a region corresponding to a center portion of the first pixel on a side of a second surface of the first base and is coupled to the first pixel; a second signal terminal that is provided in a region corresponding to a center portion of the second pixel and is coupled to the second pixel; a first shield terminal that is provided in a region corresponding to a side of the second pixel of a peripheral portion of the first pixel on the side of the second surface; and a second shield terminal that is provided in a region corresponding to a side of the first pixel of a peripheral portion of the second pixel on the side of the second surface and is provided in a region displaced in a second direction with respect to the first shield terminal.

